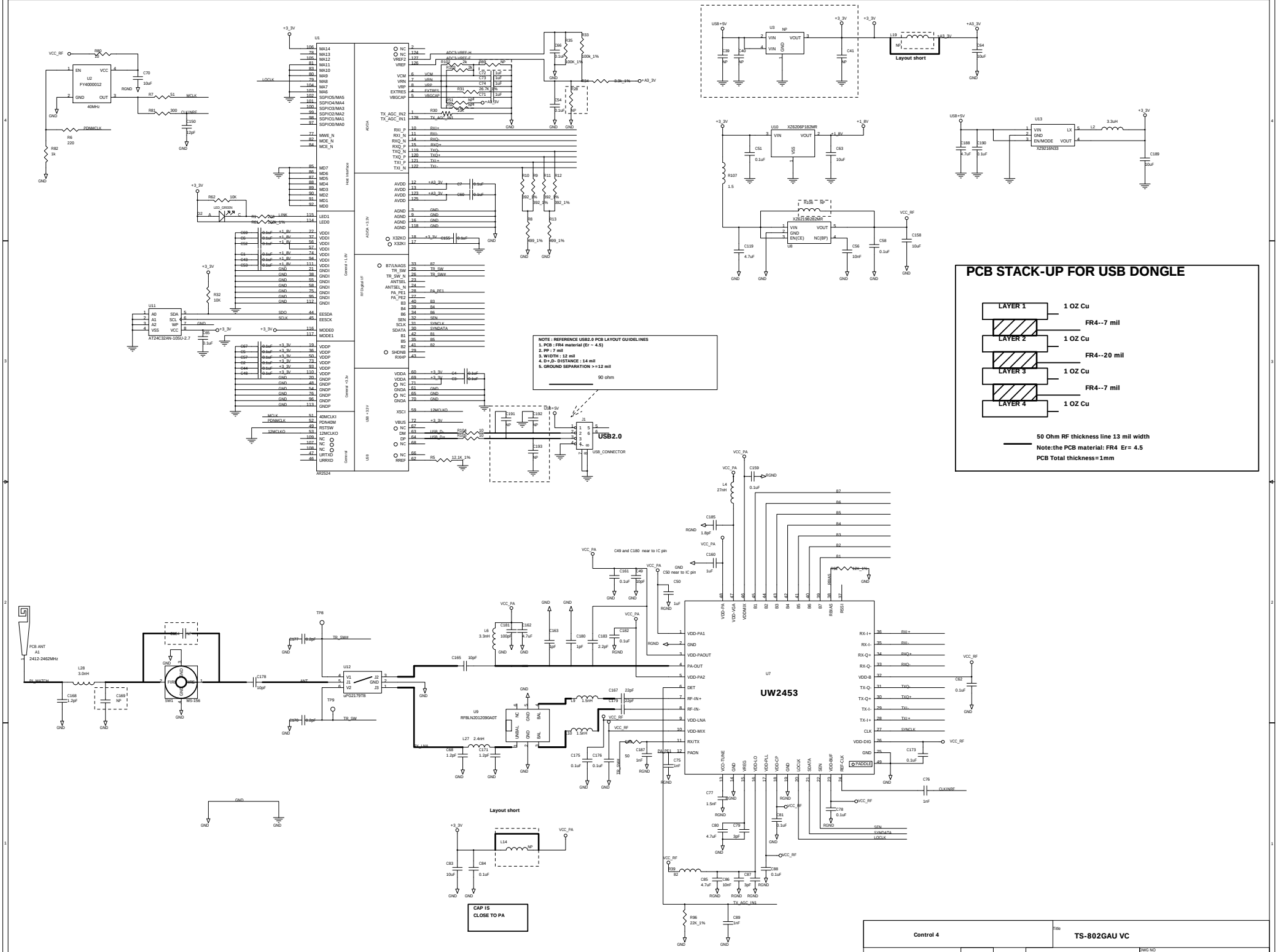
PCB STACK-UP FOR USB DONGLE
LAYER 1
1 OZ Cu
FR4--7 mil
LAYER 2
1 OZ Cu
FR4--20 mil
LAYER 3
1 OZ Cu
FR4--7 mil
LAYER 4
1 OZ Cu
50 Ohm RF thickness line 13 mil width
Note:the PCB material: FR4 Er= 4.5
PCB Total thickness=1mm
NOTE : REFERENCE USB2.0 PCB LAYOUT GUIDELINES
1. PCB : FR4 material (Er = 4.5)
2. PP : 7 mil
3. WIDTH : 12 mil
4. D+,D- DISTANCE : 14 mil
5. GROUND SEPARATION >=12 mil
90 ohm
USB2.0
UW2453
U7
U1
AR2524
U2
FY4000012
40MHz
U11
AT24C32AN-10SU-2.7
U12
uPG2179TB
U9
RFBLN20120902A0T
U13
XZ9216A33
U10
XZ6206P182MR
XZ6219B282MR
J1
USB_CONNECTOR
PCB ANT
A1
2412-2462MHz
SW1
MS-156
Layout short
CAP IS
CLOSE TO PA
C49 and C180 near to IC pin
C50 near to IC pin
Control 4
TS-802GAU VC
Date 2010.09.29
Size A1
Rev 001
Sheet 1 of 1
DWG NO